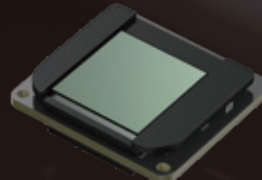
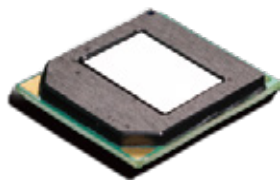
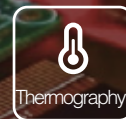


Wafer Level Package Uncooled Infrared Detectors

The Popularity of Infrared Application in Emerging Markets



Description

Wafer level packaging (WLP) is the process of completing high vacuum packaging directly on the entire MEMS wafer, then scribing and cutting to make a single infrared detector. WLP IR detectors are mainly designed to meet the miniaturization and low cost requirements of infrared technology applications in consumer electronics market. Global Sensor Technology, with volume production capability, is now offering various WLP infrared module solutions to boost more applications of emerging markets.

Easier Integration

- Ultra-small size
- Ultra-light weight
- TECless technology

Optimal & Sharp Imaging

- High sensitivity, typical NETD < 40mK
- Excellent image quality with frame rate at 50Hz

Meet Growing Demands

- Volume production at lower cost



Specifications

Model	GST612W	GST417W	GST212W
Sensitive Material	Vanadium Oxide		
Resolution	640×512	400×300	256×192
Pixel Size	12μm	17μm	12μm
Spectral Range	8-14μm		
Typical NETD	<40mK		
Digital Output	Built-in 14 bits ADC		
Thermal Time Constant	<12ms		
Max Frame Rate	50Hz	50Hz	30Hz
Power Consumption	≤220mW	≤180mW	≤75mW
Size (mm)	18×16×2.75 (Without Interface)	18×16×2.75 (Without Interface)	10.53×7.44×1.45 (Without PCB Board)
Weight	<2g	<2g	<0.5g
Operating Temperature	-40°C ~ +85°C		

Specifications are subject to change without prior notice.

Wuhan Global Sensor Technology Co., Ltd

+86 27 81298493

marketing@gst-ir.com

www.gst-ir.net

No. 6 Huanglongshan South Rd, Wuhan 430205, P.R.China